

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings of claims in the application:

Listing of Claims:

1-17. (canceled)

1 18. (previously presented) A method as in claim 24 wherein step (b) advances
2 curing of the thermosetting resin.

19. (canceled)

1 20. (previously presented) A method as in claim 24 further comprising a step of
2 inspecting the semiconductor device.

1 21. (previously presented) A method as in claim 24 wherein the semiconductor
2 device comprises an integrated circuit.

1 22. (previously presented) A method as in claim 24 wherein step (a) includes a
2 transfer molding process.

1 23. (previously presented) A method as in claim 24 wherein step (a) includes a
2 potting process.

1 24. (Currently amended) A method of making a semiconductor device
2 comprising:

3 (a) sealing the semiconductor device in a package by surrounding it with
4 thermosetting resin and thermally curing the resin at a first temperature;

5 (b) baking the thermosetting resin at a second temperature [[not]] higher than
6 the first temperature, wherein the second temperature is between about 220°C and about 260°C;
7 and

8 (e) ~~— further baking the thermosetting resin at a third temperature higher than~~
9 ~~the first temperature; and~~
10 [[d)](c) inspecting the semiconductor device.

1 25. (previously presented) A method as in claim 24 wherein a conductive lead is
2 adhesively affixed to a main surface of the semiconductor device.

1 26. (previously presented) A method as in claim 25 wherein the conductive lead
2 is adhesively affixed to a peripheral portion of the main surface of the semiconductor device.

1 27. (previously presented) A method as in claim 26 wherein an electrode of the
2 semiconductor device is electrically connected to the conductive lead.

28-30 (canceled)